OMRON

XF2

Low-profile FPC connectors with 0.3/0.5 mm-pitch

Series Additions

Original backlock mechanism ensures greater work efficiency and higher reliability.

FPC Connectors

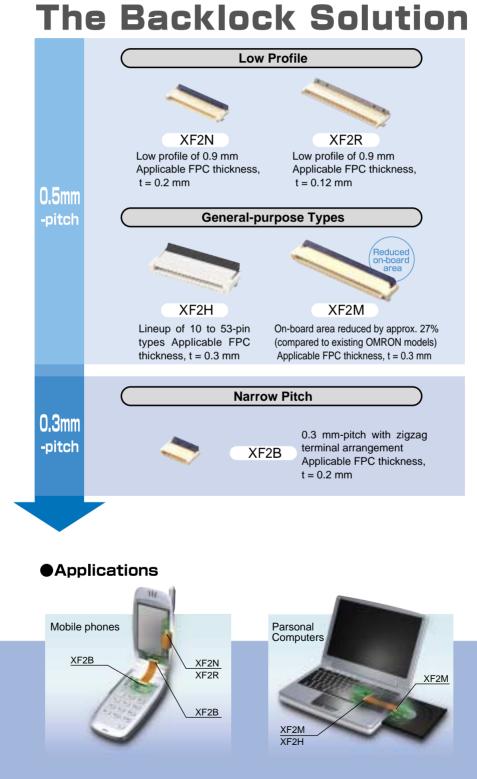
Wide Variety from ZIF (Zero Insertion Force) to Non-ZIF



FPC See How Far FPC Connectors Have Advanced

FPC connectors must offer easy operation and secure mounting in tight work spaces. The unique construction of the XF2 Series solves all FPC mounting problems and significantly enhances work efficiency and reliability.

Meeting the rapidly increasing need for smaller dimensions, slimmer profiles, and greater functionality:



Locking Types

XF2M

Reduced On-board Area 0.5 mm-pitch On-board profile of 2 mm Rotary backlock mechanism Double-sided contacts SMT terminals

XF2L

SMT terminals

Smallest On-board Area in the Industry 0.5 mm-pitch On-board profile of 1.2 mm Slide-locking mechanism Upper-contact type

XF2L

Smallest On-board Area in the Industry

0.5 mm-pitch On-board profile of 1.2 mm Slide-locking mechanism Lower-contact type SMT terminals

XF2R

Low Profile Type 0.5 mm-pitch On-board profile of 0.9 mm Rotary backlock mechanism Double-sided contacts SMT terminals

XF2N

Low Profile Type 0.5 mm-pitch On-board profile of 0.9 mm Rotary backlock mechanism Double-sided contacts SMT terminals

XF2B

0.3 mm-pitch Type 0.3 mm-pitch On-board profile of 1.2 mm Rotary backlock mechanism Double-sided contacts SMT terminals

XF2J

Top Entry, ZIF Type 0.5 mm-pitch On-board profile of 4.15 mm Slide-locking mechanism Single-sided contacts SMT terminals

形XF2H

Standard Type 0.5 mm-pitch On-board profile of 2 mm Rotary backlock mechanism Double-sided contacts SMT terminals

₩XF2G Top Entry, Non-ZIF Type

0.5 mm-pitch On-board profile of 4.15 mm Single-sided contacts SMT terminals

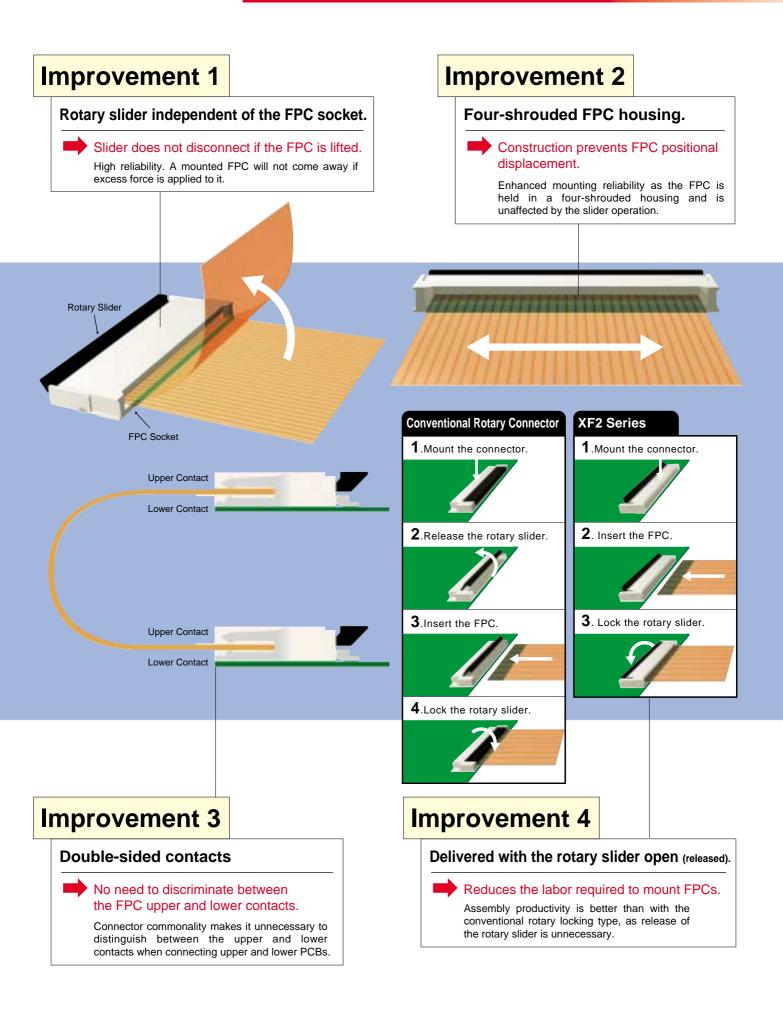
形XF2E

Low Profile, Non-ZIF Type 0.8 mm-pitch On-board profile of 1.5 mm Double-sided contacts SMT terminals

N-ZIF



Features of Rotary Backlock Mechanism



XF2B/XF2N

applications.

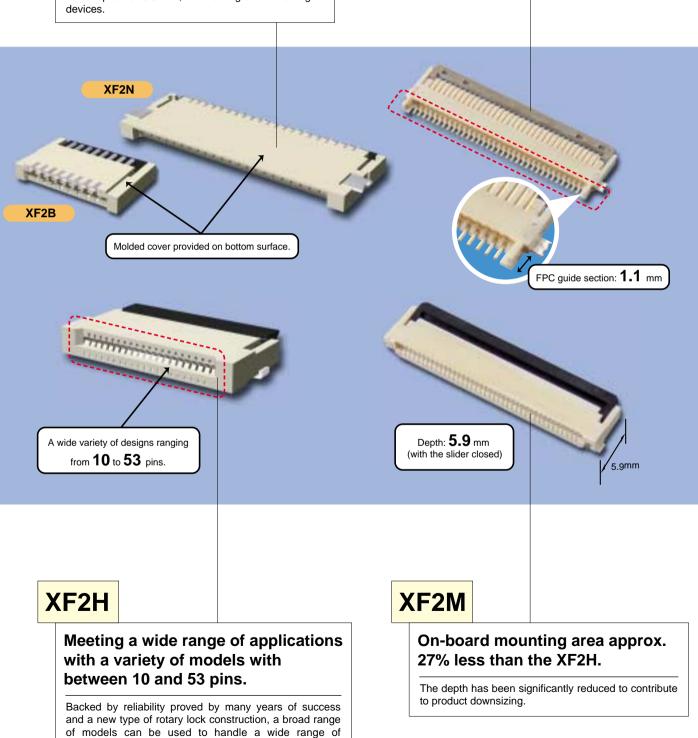
PCB design freedom increased with bottom wall and low profile.

The provision of a bottom wall eliminates exposure of terminals on the reverse side of the connector. The XF2N and XF2B have low on-board profiles of 0.9 mm and 1.2 mm respectively and the XF2B boasts a narrow pitch of 0.3 mm, contributing to downsizing of devices.

XF2R

Improved FPC insertion sensation.

The provision of an FPC guide section makes FPC insertion easier and improves work efficiency. The effective interface length has been increased to ensure greater reliability.





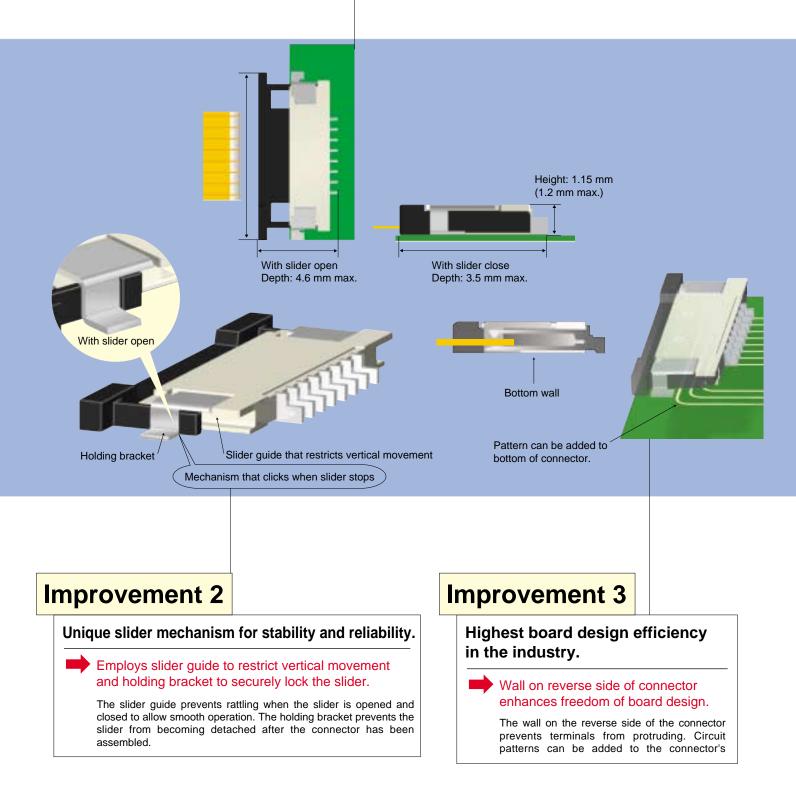
Features of XF2L Slide-locking Mechanism

Improvement 1

Occupies the smallest on-board area and volume in the industry.

Smallest on-board area and volume in the industry achieves reduced equipment size, thickness, and weight.

Ultra-compact size: 18.9 mm (W) Å~ 3.5 mm (D) Å~ 1.2 mm (H)*1 for 30-pin models. *1: A maximum of 1.2 mm including tolerance.



Rotary Backlock Type (0.3 mm-pitch)

XF2B

Rotary Backlock Mechanism and 0.3 mm-pitch Design

- Wall provided on reverse side of connector to allow greater freedom of board design.
- Double-sided (upper and lower) contact structure enables component reductions.
- Applicable FPC thickness, t = 0.2 mm. Gold-plated type.
- Use FPCs with the construction recommended by OMRON. (Refer to specifications for details.)

Specifications

Rated current	0.2A AC/DC
Rated voltage	50V AC/DC
Contact resistance	50m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Dimensions

0.6

A

A A

XF2B- 45-31A

0.6 (1.1)

0000

Table of Dimensions

Model

XF2B-1745-31A

XF2B-2345-31A

Pins

17

23

0000

1,2

в

4.8

6.6

0.1

С

5.5

7.3

0.55

D

7.0

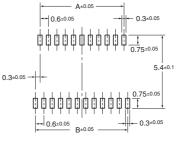
8.8



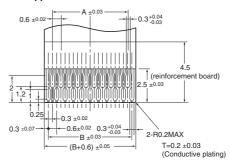
Materials/Finish

Housing	LCP resin (UL94V-0) / natural
Slider	LCP resin (UL94V-0) / black
Contact	Spring copper alloy/nickel substrate (2µm), gold-plated contacts (0.15µm)

Printed Circuit Board Matching Dimensions (Top View)







Ordering Information

Pins note 1	Model	Quantity per reel note 2	
17	XF2B-1745-31A	1.500	
23	XF2B-2345-31A	1,500	

Α

4.2

6.0

note 1. Consult your OMRON representative for enquiries related to pin-number specifications. note 2. Order an integer multiple of the quantity per reel.

0.5

0.5+ +1.23

8

Pins

21

32

Low-profile Rotary Backlock Type (0.5 mm-pitch)

Greater Freedom of Board Design with 0.9-mm **Profile and Bottom Wall**

- Backlock mechanism makes FPC mounting significantly easier.
- Double-sided (upper and lower) contact structure enables component reductions.
- Applicable FPC thickness, t = 0.2 mm. Gold-plated type.
- Use FPCs with the construction recommended by OMRON. (Refer to specifications for details.)

Specifications

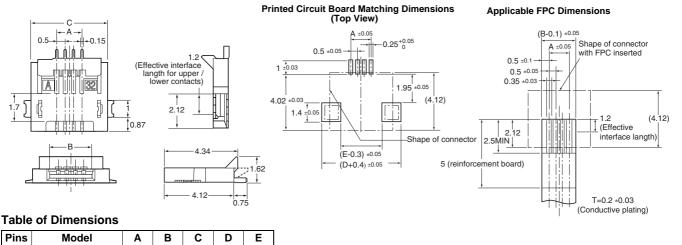
Rated current	0.3A AC/DC
Rated voltage	50V AC/DC
Contact resistance	40m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100 M min. (at 250 V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Materials/Finish

Housing	LCP resin (UL94V-0)/natural
Slider	LCP resin (UL94V-0)/black
Contact	Spring copper alloy/nickel substrate (1.5µm), gold-plated contacts (0.15µm)
Hold-down	Spring copper alloy/fused-tin plating (1.5µm)

Dimensions

XF2N- 015-3



Ordering Information

XF2N-2115-3

XF2N-3215-3

Pins note 1	Model	Quantity per reel note 2	
21	XF2N-2115-3	3.000	
32	XF2N-3215-3	3,000	

10.0

15.5

11.1

16.6

13.0

18.5

13.8

19.3

11.8

17.3

note 1. Consult your OMRON representative for enquiries related to pin-number specifications.

note 2. Order an integer multiple of the quantity per reel.



Low-profile Rotary Backlock Type (0.5 mm-pitch)

XF2R

- Applicable FPC thickness, t = 0.12 mm. Gold-plated type.
- Use FPCs with the construction recommended by OMRON. (Refer to specifications for details.)

Specifications

Rated current	0.3A AC/DC
Rated voltage	50V AC/DC
Contact resistance	40m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100 M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Dimensions

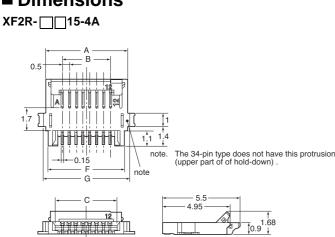


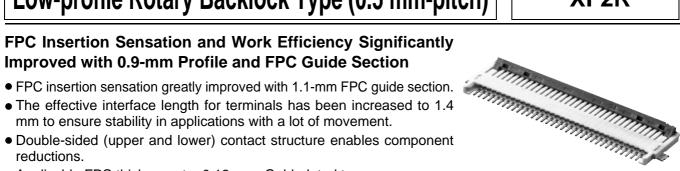
Table of Dimensions

Pins	Model	Α	В	С	D	Е	F	G
6	XF2R-0615-4A	5.0	2.5	3.6	6.1	4.1	4.55	5.35
9	XF2R-0915-4A	6.5	4.0	5.1	7.6	5.6	6.05	6.85
18	XF2R-1815-4A	11.0	8.5	9.6	12.1	10.1	10.55	11.35
24	XF2R-2415-4A	14.0	11.5	12.6	15.1	13.1	13.55	14.35
34	XF2R-3415-4A	19.0	16.5	17.6	20.1	18.1	18.55	-
40	XF2R-4015-4A	22.0	19.5	20.6	23.1	21.1	21.55	22.35

Ordering Information

Pins note 1	Model	Pins note 1	Model	Quantity per reel note 2
6	XF2R-0615-4A	24	XF2R-2415-4A	
9	XF2R-0915-4A	34	XF2R-3415-4A	3,000
18	XF2R-1815-4A	40	XF2R-4015-4A	

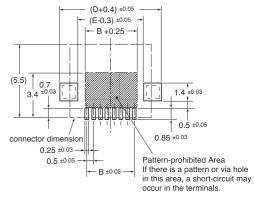
note 1. Consult your OMRON representative for enquiries related to pin-number specifications. note 2. Order an integer multiple of the quantity per reel.



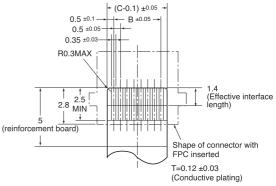
Materials/Finish

Housing	LCP resin (UL94V-0)/natural
Slider	LCP resin (UL94V-0)/brown
Contact	Spring copper alloy/nickel substrate (1.5 µ m), gold-plated contacts (0.15 µ m)
Hold-down	Spring copper alloy/fused-tin plating (1.5 µ m)

Printed Circuit Board Matching Dimensions (Top View)



Applicable FPC Dimensions



Reduced-area Rotary Backlock Type (0.5 mm-pitch)

Reduced-area Type Requires Approx. 27% Less On-board mounting area than the XF2H

- Short body with depth of 5.9 mm (with slider closed).
- Environment-friendly type that eliminates lead from solder is available as a standard product.
- Double-sided (upper and lower) contact structure enables component reductions.
- Applicable FPC thickness, t = 0.3 mm.

Specifications

Rated current	0.5A AC/DC
Rated voltage	50V AC/DC
Contact resistance	40m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100 M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Dimensions

XF2M- 15-1F

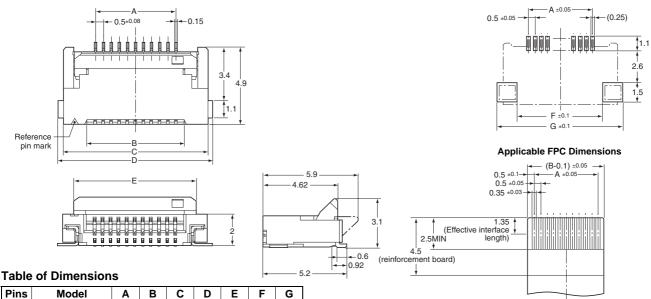
Materials/Finish

Housing	LCP resin (UL94V-0)/natural
Slider	LCP resin (UL94V-0)/black
Contact	Spring copper alloy/nickel substrate (2 µ m), tin-alloy plating (2 µ m)
Hold-down	Spring copper alloy/fused-tin plating (1.5 µ m)

Printed Circuit Board Matching Dimensions (Top View)

T=0.3 ±0.05

(Conductive plating)



Ordering Information

XF2M-4015-1F

XF2M-5015-1F

Pins note 1	Model	Quantity per reel note 2		
40	XF2M-4015-1F	1.500		
50	XF2M-5015-1F	1,500		

19.5

20.6

23.5 24.1

24.5 25.6 28.5 29.1 27.1 26.1 29.5

note 1. Consult your OMRON representative for enquiries related to pin-number specifications. note 2 Order an integer multiple of the quantity per reel.

22.1 21.1

24.5

40

50

New rotary lock concept achieves high reliability and superior work efficiency.

- The unique rotary lock construction significantly improves work efficiency during FPC mounting.
- Double-sided contacts maintain a stable contact force. Discrimination between FPC upper and lower contacts in unnecessary.
- Applicable FPC thickness, t = 0.3 mm.

Specifications

-	
Rated current	0.5A AC/DC
Rated voltage	50V AC/DC
Contact resistance	30m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100 M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	20 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

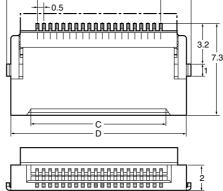
Dimensions

XF2H- 15-1LW



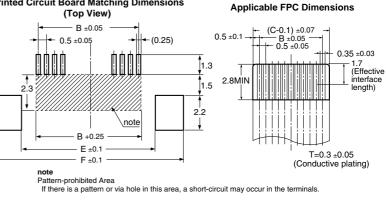
Table of Dimensions

Pins	Model	Α	В	С	D	Е	F
10	XF2H-1015-1LW	9.1	4.5	5.6	8.5	6.5	10.1
12	XF2H-1215-1LW	10.1	5.5	6.6	9.5	7.5	11.1
13	XF2H-1315-1LW	10.6	6.0	7.1	10.0	8.0	11.6
14	XF2H-1415-1LW	11.1	6.5	7.6	10.5	8.5	12.1
18	XF2H-1815-1LW	13.1	8.5	9.6	12.5	10.5	14.1
20	XF2H-2015-1LW	14.1	9.5	10.6	13.5	11.5	15.1
21	XF2H-2115-1LW	14.6	10.0	11.1	14.0	12.0	15.6
22	XF2H-2215-1LW	15.1	10.5	11.6	14.5	12.5	16.1
24	XF2H-2415-1LW	16.1	11.5	12.6	15.5	13.5	17.1
25	XF2H-2515-1LW	16.6	12.0	13.1	16.0	14.0	17.6
26	XF2H-2615-1LW	17.1	12.5	13.6	16.5	14.5	18.1
28	XF2H-2815-1LW	18.1	13.5	14.6	17.5	15.5	19.1
30	XF2H-3015-1LW	19.1	14.5	15.6	18.5	16.5	20.1
32	XF2H-3215-1LW	20.1	15.5	16.6	19.5	17.5	21.1
33	XF2H-3315-1LW	20.6	16.0	17.1	20.0	18.0	21.6
34	XF2H-3415-1LW	21.1	16.5	17.6	20.5	18.5	22.1
35	XF2H-3515-1LW	21.6	17.0	18.1	21.0	19.0	22.6
36	XF2H-3615-1LW	22.1	17.5	18.6	21.5	19.5	23.1
38	XF2H-3815-1LW	23.1	18.5	19.6	22.5	20.5	24.1
40	XF2H-4015-1LW	24.1	19.5	20.6	23.5	21.5	25.1
42	XF2H-4215-1LW	25.1	20.5	21.6	24.5	22.5	26.1
45	XF2H-4515-1LW	26.6	22.0	23.1	26.0	24.0	27.6
50	XF2H-5015-1LW	29.1	24.5	25.6	28.5	26.5	30.1
53	XF2H-5315-1LW	30.6	26.0	27.1	30.0	28.0	31.6



R

Printed Circuit Board Matching Dimensions





- (8.1) 6.74

6.35

- 3.44

(1.9)

XF2H

Materials/Finish

Housing	PA6T resin (UL94V-0)/natural
Slider	LCP resin (UL94V-0)/black
Contact	Spring copper alloy/nickel substrate (2 µ m), tin-alloy plating (2 µ m)
Hold-down	Spring copper alloy/fused-tin plating (1.5 µ m)

Ordering Information

Pins note 1	Model	Pins note 1	Model	Pins note 1	Model	Quantity per reel note 2
10	XF2H-1015-1LW	24	XF2H-2415-1LW	35	XF2H-3515-1LW	
12	XF2H-1215-1LW	25	XF2H-2515-1LW	36	XF2H-3615-1LW	
13	XF2H-1315-1LW	26	XF2H-2615-1LW	38	XF2H-3815-1LW	
14	XF2H-1415-1LW	28	XF2H-2815-1LW	40	XF2H-4015-1LW	1 500
18	XF2H-1815-1LW	30	XF2H-3015-1LW	42	XF2H-4215-1LW	1,500
20	XF2H-2015-1LW	32	XF2H-3215-1LW	45	XF2H-4515-1LW	
21	XF2H-2115-1LW	33	XF2H-3315-1LW	50	XF2H-5015-1LW	
22	XF2H-2215-1LW	34	XF2H-3415-1LW	53	XF2H-5315-1LW	

note 1. Consult your OMRON representative for enquiries related to pin-number specifications.

note 2. Order an integer multiple of the quantity per reel. We will also accept small lot orders (for 100 or 500 units). When ordering, please specify model numbers that end with -R100 for 100 units or -R500 for 500 units.

ZIF Slide-locking Type (0.5 mm-pitch)

XF2L

XF2L

(Lower-contact Type)

LCP resin (UL94V-0)/

Greater Freedom of Board Design with Smallest On-board Area in Industry and Bottom Wall

- Occupies the smallest on-board area and volume in the industry.
- Low on-board profile of only 1.2 mm max.
- Highest efficiency with board design surfaces in the industry with bottom wall preventing terminal exposure.
- Construction employs secure locking mechanism.
- Applicable FPC thickness, t = 0.3 mm.

Specifications

Rated current	0.5A AC/DC
Rated voltage	50V AC/DC
Contact resistance	30m max. (at 20 mV DC max., 100 mA max.)
Insulation resistance	100 M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	30 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Dimensions

XF2L- 5-1 Applicable FPC Dimensions (D-0.1) ±0.05 0.5 +0.1 ±0.05 0.5 ±0.05 0.35 ±0.03 1 35 (Effective interface length) -0.5 +0.08 (0.2) . . 0.55 2.5 MIN 1.05 (5) ٦٢ 1 einforcement board note. 3 1 0.75 T=0.3Å}0.03 (Cnductive plating) XF2L- 25-1 (Upper-contact Type) -D -3.05 4 55 1.2 MAX. -3 45 → With slider open XF2L- 25-1 (Lower-contact Type) – D -3.05 4.55 -E-1.2 MAX 3.45 With slider open

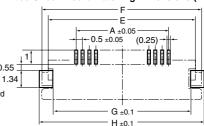
Printed Circuit Board Matching Dimensions (Top View)

LCP resin (UL94V-0)/natural

Spring copper alloy/nickel substrate (2 µm),

Spring copper alloy/fused-tin plating (1.5 µm)

brown



XF2L-___25-1

Materials/Finish

black

Model

Ordering

Housing

Contact

Hold-down

Slider

XF2L

(Upper-contact Type)

LCP resin (UL94V-0)/

tin-alloy plating (2 µm)

(Cross Section of Upper-contact Type)

XF2L-

K.	
Tananananananananananan	J

Table of Dimensions Upper-contact Type

Pins	Model	Α	В	С	D	Е	F	G	Н
4	XF2L-0425-1	1.5	5.9	6.9	2.6	5.88	6.88	5.28	7.28
6	XF2L-0625-1	2.5	6.9	7.9	3.6	6.88	7.88	6.28	8.28
7	XF2L-0725-1	3.0	7.4	8.4	4.1	7.38	8.38	6.78	8.78
8	XF2L-0825-1	3.5	7.9	8.9	4.6	7.88	8.88	7.28	9.28
9	XF2L-0925-1	4.0	8.4	9.4	5.1	8.38	9.38	7.78	9.78
10	XF2L-1025-1	4.5	8.9	9.9	5.6	8.88	9.88	8.28	10.28
12	XF2L-1225-1	5.5	9.9	10.9	6.6	9.88	10.88	9.28	11.28
13	XF2L-1325-1	6.0	10.4	11.4	7.1	10.38	11.38	9.78	11.78
18	XF2L-1825-1	8.5	12.9	13.9	9.6	12.88	13.88	12.28	14.28
21	XF2L-2125-1	10.0	14.4	15.4	11.1	14.38	15.38	13.78	15.78
26	XF2L-2625-1	12.5	16.9	17.9	13.6	16.88	17.88	16.28	18.28
30	XF2L-3025-1	14.5	18.9	19.9	15.6	18.88	19.88	18.28	20.28

Lower-contact Type

Pins	Model	Α	В	С	D	Е	F	G	Н	
5	XF2L-0535-1	2.0	6.4	7.4	3.1	6.38	7.38	5.78	7.78	
6	XF2L-0635-1	2.5	6.9	7.9	3.6	6.88	7.88	6.28	8.28	
7	XF2L-0735-1	3.0	7.4	8.4	4.1	7.38	8.38	6.78	8.78	
8	XF2L-0835-1	3.5	7.9	8.9	4.6	7.88	8.88	7.28	9.28	
10	XF2L-1035-1	4.5	8.9	9.9	5.6	8.88	9.88	8.28	10.28	
12	XF2L-1235-1	5.5	9.9	10.9	6.6	9.99	10.88	9.28	11.28	
13	XF2L-1335-1	6.0	10.4	11.4	7.1	10.38	11.38	9.78	11.78	
15	XF2L-1535-1	7.0	11.4	12.4	8.1	11.38	12.38	10.78	12.78	
18	XF2L-1835-1	8.5	12.9	13.9	9.6	12.88	13.88	12.28	14.28	
19	XF2L-1935-1	9.0	13.4	14.4	10.1	13.38	14.38	12.78	14.78	
20	XF2L-2035-1	9.5	13.9	14.9	10.6	13.88	14.88	13.28	15.28	
22	XF2L-2235-1	10.5	14.9	15.9	11.6	14.88	15.88	14.28	16.28	
24	XF2L-2435-1	11.5	15.9	16.9	12.6	15.88	16.88	15.28	17.28	
30	XF2L-3035-1	14.5	18.9	19.9	15.6	18.88	19.88	18.28	20.28	



Ordering Information

Pins note 1	Туре	Model	Pins note 1	Туре	Model	Pins note 1	Туре	Model	Quantity per reel note 2
4	Upper-contact	XF2L-0425-1	10	Upper-contact	XF2L-1025-1	19	Lower-contact	XF2L-1935-1	
5	Lower-contact	XF2L-0535-1	10	Lower-contact	XF2L-1035-1	20	Lower-contact	XF2L-2035-1	Ī
6	Upper-contact	XF2L-0625-1	12	Upper-contact	XF2L-1225-1	21	Upper-contact	XF2L-2125-1	Ī
0	Lower-contact	XF2L-0635-1	12	Lower-contact	XF2L-1235-1	22	Lower-contact	XF2L-2235-1	Ī
7	Upper-contact	XF2L-0725-1	13	Upper-contact	XF2L-1325-1	24	Lower-contact	XF2L-2435-1	3,000
· /	Lower-contact	XF2L-0735-1	13	Lower-contact	XF2L-1335-1	26	Upper-contact	XF2L-2625-1	Ī
8	Upper-contact	XF2L-0825-1	15	Lower-contact	XF2L-1535-1	- 30	Upper-contact	XF2L-3025-1	Ī
0	Lower-contact	XF2L-0835-1	18	Upper-contact	XF2L-1825-1	- 30	Lower-contact	XF2L-3035-1	1
9	Upper-contact	XF2L-0925-1	10	Lower-contact	XF2L-1835-1	-	-	-	Ī

note 1. Consult your OMRON representative for enquiries related to pin-number and lead-free plating specifications.

note 2. Order an integer multiple of the quantity per reel.

note 3. Use polyimide and thermoset adhesive for reinforcement film material.

ZIF Slide-locking Type (0.5 mm-pitch)

Top-entry ZIF Connector

- Low on-board profile of only 4.15 mm.
- Adhesion face on top of the connector suits automatic mounting.
- Models with reverse terminal arrangement also available.
- Applicable FPC thickness, t = 0.3 mm.

0.5 ±0.1

змім

Specifications

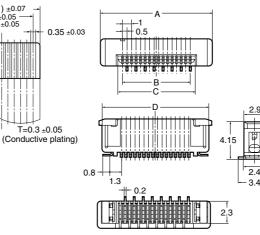
Rated current	0.5A AC/DC
Rated voltage	50V AC/DC
Contact resistance	30m max. (at 20 mV max., 100 mA max.)
Insulation resistance	100 M min. (at 250V DC)
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)
Insertion tolerance	30 times
Ambient operating temperature	-30 to +85°C (with no icing or condensation)

Dimensions

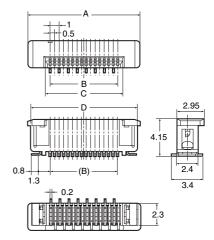
XF2J- 🗌 24-11



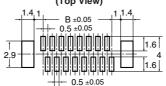
Applicable FPC Dimensions Standard Terminal Arrangement ← (C-0.1) ±0.07 → → B ±0.05 → → → 0.5 ±0.05



Reverse Terminal Arrangement



Printed Circuit Board Matching Dimensions (Top View) Printed Circuit Board Matching Dimensions (Top View)



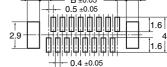


Table of Dimensions

	Мо					
Pins	Standard Terminal Arrangement	Reverse Terminal Arrangement	Α	В	С	D
6	XF2J-0624-11	XF2J-0624-12	7.5	2.5	3.6	6.9
8	XF2J-0824-11	XF2J-0824-12	8.5	3.5	4.6	7.9
10	XF2J-1024-11	XF2J-1024-12	9.5	4.5	5.6	8.9
12	XF2J-1224-11	XF2J-1224-12	10.5	5.5	6.6	9.9
14	XF2J-1424-11	-	11.5	6.5	7.6	10.9
16	XF2J-1624-11	XF2J-1624-12	12.5	7.5	8.6	11.9
18	XF2J-1824-11	XF2J-1824-12	13.5	8.5	9.6	12.9
20	XF2J-2024-11	XF2J-2024-12	14.5	9.5	10.6	13.9
22	XF2J-2224-11	XF2J-2224-12	15.5	10.5	11.6	14.9
24	XF2J-2424-11	XF2J-2424-12	16.5	11.5	12.6	15.9
26	XF2J-2624-11	-	17.5	12.5	13.6	16.9
28	XF2J-2824-11	-	18.5	13.5	14.6	17.9
30	XF2J-3024-11	-	19.5	14.5	15.6	18.9

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Materials/Finish

Housing	PA46 resin (UL94V-0)/natural
Slider	PPS resin (UL94V-0)/black LCP resin (UL94V-0)/black
Contact	Spring copper alloy/nickel substrate (2 µ m), tin-alloy plating (2 µ m)
Hold-down	Spring copper alloy/fused-tin plating (1.5 µ m)

Ordering Information

Pins	Model		Quantity par real
note 1	Standard Terminal Arrangement	Reverse Terminal Arrangement	Quantity per reel note 2
6	XF2J-0624-11	XF2J-0624-12	
8	XF2J-0824-11	XF2J-0824-12	
10	XF2J-1024-11	XF2J-1024-12	
12	XF2J-1224-11	XF2J-1224-12	
14	XF2J-1424-11	-	
16	XF2J-1624-11	XF2J-1624-12	
18	XF2J-1824-11	XF2J-1824-12	1,000
20	XF2J-2024-11	XF2J-2024-12	
22	XF2J-2224-11	XF2J-2224-12	
24	XF2J-2424-11	XF2J-2424-12	
26	XF2J-2624-11	-	
28	XF2J-2824-11	-	
30	XF2J-3024-11	-	

note 1. Consult your OMRON representative for enquiries related to pin-number and lead-free plating specifications.

note 2. Order an integer multiple of the quantity per reel.

note 3. We will also accept small lot orders (for 100 or 500 units). When ordering, please specify model numbers that end with -R100 for 100 units or -R500 for 500 units.

Non-ZIF Type (0.5 mm-pitch)

XF2G

Top-entry ZIF Connector

- Low on-board profile of only 4.15 mm.
- Adhesion face on top of the connector suits automatic mounting.
- Applicable FPC thickness, t = 0.3 mm.

Specifications

Rated current	0.5A AC/DC	
Rated voltage	50V AC/DC	
Contact resistance	30m max. (at 20 mV max., 100 mA max.)	
Insulation resistance	100 M min. (at 250V DC)	
Withstand voltage	250V AC for 1 min. (leakage current: 1 mA max.)	
Insertion tolerance	10 times	
Ambient operating temperature	-30 to +85°C (with no icing or condensation)	

ВС

7.5

13.9 12.5 11.5

6.5

7.5

Α

4.9 3.5 2.5

8.9

9.9 8.5

XF2G-2614-11 14.9 13.5 12.5

Dimensions

XF2G- 14-11



Table of Dimensions

Model

XF2G-0614-11

XF2G-1414-11

XF2G-1614-11

XF2G-2414-11

Pins

6

14

16

24

26

В

Materials/Finish

2 95

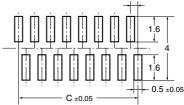
2.4

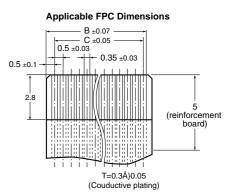
3.4

4.15

Housing	PA46 resin (UL94V-0)/natural
Contact	Spring copper alloy/nickel substrate (2 µ m), tin-alloy plating (2 µ m)

Printed Circuit Board Matching Dimensions (Top View)





Ordering Information

Pins note 1	Model	Quantity per reel note 2
6	XF2G-0614-11	
14	XF2G-1414-11	
16	XF2G-1614-11	1,000
24	XF2G-2414-11	
26	XF2G-2614-11	

note 1. Consult your OMRON representative for enquiries related to pin-number specifications. note 2 Order an integer multiple of the quantity per reel.

Non-ZIF Type (0.8 mm-pitch)

18

- Low on-board profile of only 1.5 mm.
- Double-sided contacts maintain a stable contact force. Discrimination between FPC upper and lower contacts in unnecessary.
- Applicable FPC thickness, t = 0.3 mm..

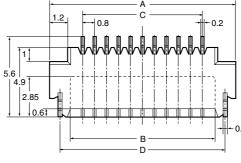
Specifications

Rated current	0.5A AC/DC	
Rated voltage	50V AC/DC	
Contact resistance	30m max. (at 20 mV max., 100 mA max.)	
Insulation resistance	100 M min. (at 250V DC)	
Withstand voltage	500V AC for 1 min. (leakage current: 1 mA max.)	
Insertion tolerance	10 times	
Ambient operating temperature	-30 to +85°C (with no icing or condensation)	

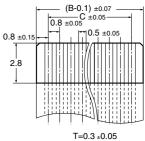
Dimensions

XF2E- 15-1





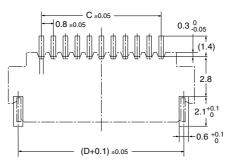
Applicable FPC Dimensions



(Conductive plating)



Pins	Model	Α	В	С	D
5	XF2E-0515-1	7.6	4.9	3.2	6.2
6	XF2E-0615-1	8.4	5.7	4.0	7.0
7	XF2E-0715-1	9.2	6.5	4.8	7.8
8	XF2E-0815-1	10.0	7.3	5.6	8.6
9	XF2E-0915-1	10.8	8.1	6.4	9.4
10	XF2E-1015-1	11.6	8.9	7.2	10.2
12	XF2E-1215-1	13.2	10.5	8.8	11.8
15	XF2E-1515-1	15.6	12.9	11.2	14.2
17	XF2E-1715-1	17.2	14.5	12.8	15.8
20	XF2E-2015-1	19.6	16.9	15.2	18.2



Ordering Information

Pins note 1	Model	Pins note 1	Model	Quantity per reel note 2
5	XF2E-0515-1	10	XF2E-1015-1	
6	XF2E-0615-1	12	XF2E-1215-1	
7	XF2E-0715-1	15	XF2E-1515-1	4,000
8	XF2E-0815-1	17	XF2E-1715-1	
9	XF2E-0915-1	20	XF2E-2015-1	

note 1. Consult your OMRON representative for enquiries related to pin-number specifications. note 2. Order an integer multiple of the quantity per reel.

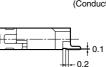
TELE

Materials/Finish

Housing	Glass-filled modified PA resin (UL94V-0)/milk white
Contact	Spring copper alloy/nickel substrate (2 μ m), tin-alloy plating (2 μ m)
Hold-down Copper-alloy/copper substrate (2 µ m), tin-alloy plating (2 µ m)	

Basic Pattern Dimensions (Reference)





04





XF2E

Common Precautions for XF2 Connectors

Precautions

Correct Use

Backlock Types

- Do not lock the slider without an FPC inserted. Locking the slider without an FPC inserted will cause a decrease in the dimensions between the contacts and consequently an increase in the force required to insert an FPC.
- When designing the board, be sure to allow locking space for the slider (i.e., space for the slider when it is locked).
- The connector has a double-sided contact structure and so be sure to insert the FPC with the correct orientation.
- When locking the slider, press it down securely with your fingers at both ends.

Failing to lock the slider properly may result in contact failure.

· Unlocking the Slider

Unlock the slider manually. Place your index fingers at both ends of the slider and lift it up. Do not apply excessive force when lifting the slider. Doing so may result in the slider being damaged or detached. If the slider becomes detached, it may not be able to hold the FPC and contact failure may result.

All Models

- Insert the FPC right to the back of the connector. Failing to do so may result in a loss of contact reliability.
- After mounting (and locking) the FPC, do not bend or pull it with excessive force. Doing so may result in FPC disconnection.
- When bending the FPC after mounting to the PCB, do not bend it excessively near the place where it enters the connector. Doing so may result in a loss of contact reliability.
- In applications where the connector may frequently be exposed to shock or vibration, or where, as part of a mechanism, connected parts may move, secure the FPC and make sure that it is not subjected to a direct load.
- Do not perform reflow or manual soldering with the FPC inserted in the connector. Doing so may result in a loss of contact reliability.
- · Unlock the slider before removing the FPC.
- $\cdot\,$ Use an FPC with the structure recommended by OMRON.
- Do not perform reflow or manual soldering with the slider
- locked. Doing so may result in a loss of contact reliability.
- Observe a metal mask thickness of t = 0.12 to 0.15 mm.
- Metal mask open area ratio: 90% of the printed circuit board matching dimensions in the dimensions diagrams.

Recommended Reflow Conditions

	Standard reflow conditions	Reflow conditions for lead-free solder (backlock type only)
Preheating temperature	150 ± 10°C	150 to 180°C
Time	60 to 120 s	60 to 120 s
Soldering tem- perature	200 to 240°C	230 to 250°C
Time (10 s max. at the maximum temperature 240°C)	30 s max.	30 s max.

Storage

Do not store in locations close to sources of gases such ammonia gas or sulphide gas.

Do not store in locations subject to dust or high humidity levels.

ALL DIMENSIONS SHOWN ARE IN MILLIMETERS. To convert millimeters into inches, multiply by 0.03937. To convert grams into ounces, multiply by 0.03527.

Cat. No. G011-E1-02 In the interest of product improvement, specifications are subject to change without notice. OMRON Corporation

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